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Website www.midasdisplays.com

Specification

Part Number:	MCT043EC6W480272LML
Version:	
Date:	

Revision

No.	Date	Description	Item	Page

Contents

2. General Specification

This product is composed of a TFT LCD panel, driver ICs, FPC, Control Board and a backlight unit. The following table described the features of MCT043EC6W480272LML.

- Dot Matrix: 480x 3(RGB) x272
- Module dimension:105.5 x 67.2 x 2.90 (max.) mm^3
- View area: 95.04x53.856 mm^2
- Dot pitch: 0.066 x 0.198 mm2
- LCD type: TFT, Negative, Transmissive
- View direction: 6 o’clock
- Backlight Type: LED, Normally White

Midas Active Matrix Display Part Number System

MC	T	057	A	6	*	W	320240	L	M	L	*	*	*	*	*
1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16

1 = **MC:** Midas Components

2 = **T:** TFT **A:** Active Matrix OLED

3 = **Size**

4 = **Series**

5 = **Viewing Angle: 6:** 6 O'clock **12:** 12 O'clock **O:** All round

6 = **Blank:** No Touch **T:** Resistive Touchscreen **C:** Capacitive Touchscreen

7 = **Operating Temp Range: S:** 0 to 50Deg C **B:** -20+60Deg C
W: -20+70Deg C **E:** -30+85Deg C

8 = **No of Pixels**

9 = **Orientation: P:** Portrait **L:** Landscape

10 = **Mode: R:** Reflective **M:** Transmissive **T:** Transflective
S: Sunlight Readable (transmissive)
W: White on Black (Monochrome)

11 = **Backlight: Blank:** None **L:** LED **C:** CCFL

12 = **Blank:** No Module/board **C:** Controller board module

13 = **Blank:** None **V:** Video

14 = **Blank:** None **B:** Bracket

15 = **Blank:** None **H:** Host Cable

16 = **Blank:** None **K:** Keyboard

4. Interface Pin Function

4.1. TFT LCD Panel Driving Section

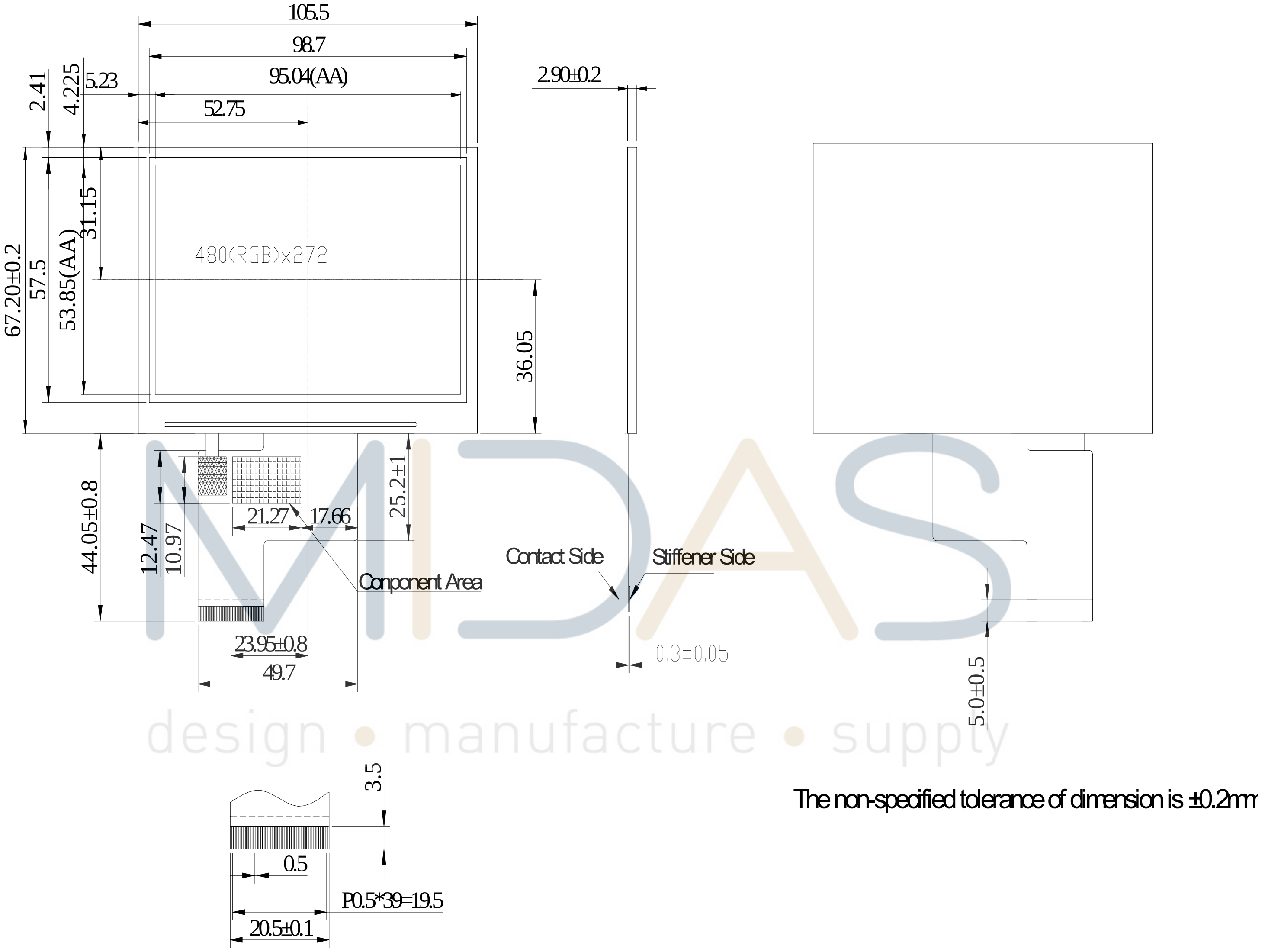
FPC Connector is used for the module electronics interface.

Pin No.	Symbol	I/O	Function	Remark
1	VLED-	P	Power for LED backlight cathode	
2	VLED+	P	Power for LED backlight anode	
3	GND	P	Power ground	
4	VDD	P	Power voltage	
5	R0	I	Red data (LSB)	
6	R1	I	Red data	
7	R2	I	Red data	
8	R3	I	Red data	
9	R4	I	Red data	
10	R5	I	Red data	
11	R6	I	Red data	
12	R7	I	Red data (MSB)	
13	G0	I	Green data (LSB)	
14	G1	I	Green data	
15	G2	I	Green data	
16	G3	I	Green data	
17	G4	I	Green data	
18	G5	I	Green data	
19	G6	I	Green data	
20	G7	I	Green data (MSB)	
21	B0	I	Blue data (LSB)	
22	B1	I	Blue data	
23	B2	I	Blue data	
24	B3	I	Blue data	

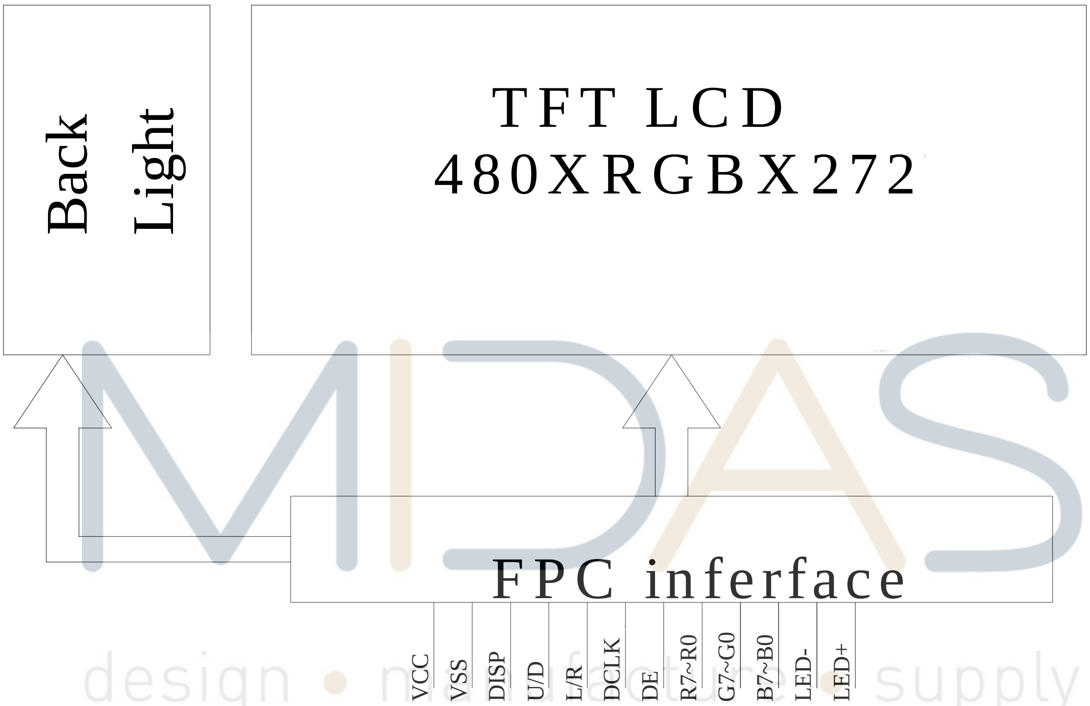
25	B4	I	Blue data	
26	B5	I	Blue data	
27	B6	I	Blue data	
28	B7	I	Blue data (MSB)	
29	GND	P	Power ground	
30	CLK	I	Pixel clock	
31	DISP	I	Display on/off	
32	NC	-	No connection	
33	NC	-	No connection	
34	DE	I	Data Enable	
35	NC	-	No connection	
36	GND	P	Power ground	
37	NC	-	No connection	
38	NC	-	No connection	
39	NC	-	No connection	
40	NC	-	No connection	

I: input, O: output, P: Power

5. Outline Dimension & Block Diagram



The non-specified tolerance of dimension is ±0.2m


Back Light
TFT LCD
480XRGBX272
FPC inferface
VCC
VSS
DISP
U/D
L/R
DCLK
DE
R7~R0
G7~G0
B7~B0
LED-
LED+

6. Display Control Instruction

6.1 Absolute Maximum Ratings.

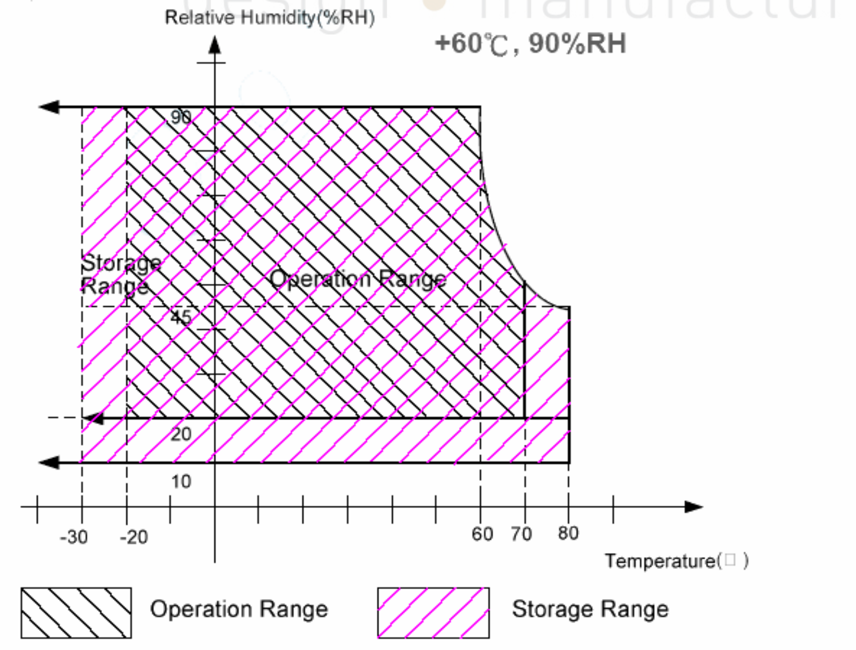
Item	Symbol	Values		Unit	Remark
		Min	max		
Power Supply Voltages	VDD	-0.5	5.0	V	
Input signal voltage	Logic input	-0.5	5.0	V	
Operating Temperature	Topa	-20	70	° C	Note3,4
Storage Temperature	Tst	-30	80	° C	Note3,4
LED Reverse Voltage	Vr	-	1.2	V	Each LED Note2
LED Forward Current	IF	-	30	MA	Each LED

Note 1: The absolute maximum rating values of this product are not allowed to be exceeded at any times. A module should be used with any of the absolute maximum ratings exceeded, the characteristics of the module may not be recovered, or in an extreme condition, the module may be permanently destroyed.

Note 2: VR Conditions: Zener Diode 20mA

Note 3: 90% RH Max. (Max wet temp. is 60℃)

Maximum wet-bulb temperature is at 60℃ or less. And No condensation (no drops of dew)



Note 4: In case of temperature below 0℃,the response time of liquid crystal (LC) becomes slower and the color of panel darker than normal one.

6.2 Typical operation conditions

Item	Symbol	Values			Unit	Remark
		Min	TYP	max		
Power voltage	VDD	3.1	3.3	3.5	V	
Current of driver	IVDD	-	TBD	25	mA	VDD =3.3V
Input logic high voltage	VIH	0.8* VDD	-	VDD	V	Note1
Input logic low voltage	VIL	GND	-	0.2 VDD	V	

Note1: CLK, DE, R0~ R7, G0~ G7, B0~ B7.

6.3 Backlight Driving Conditions

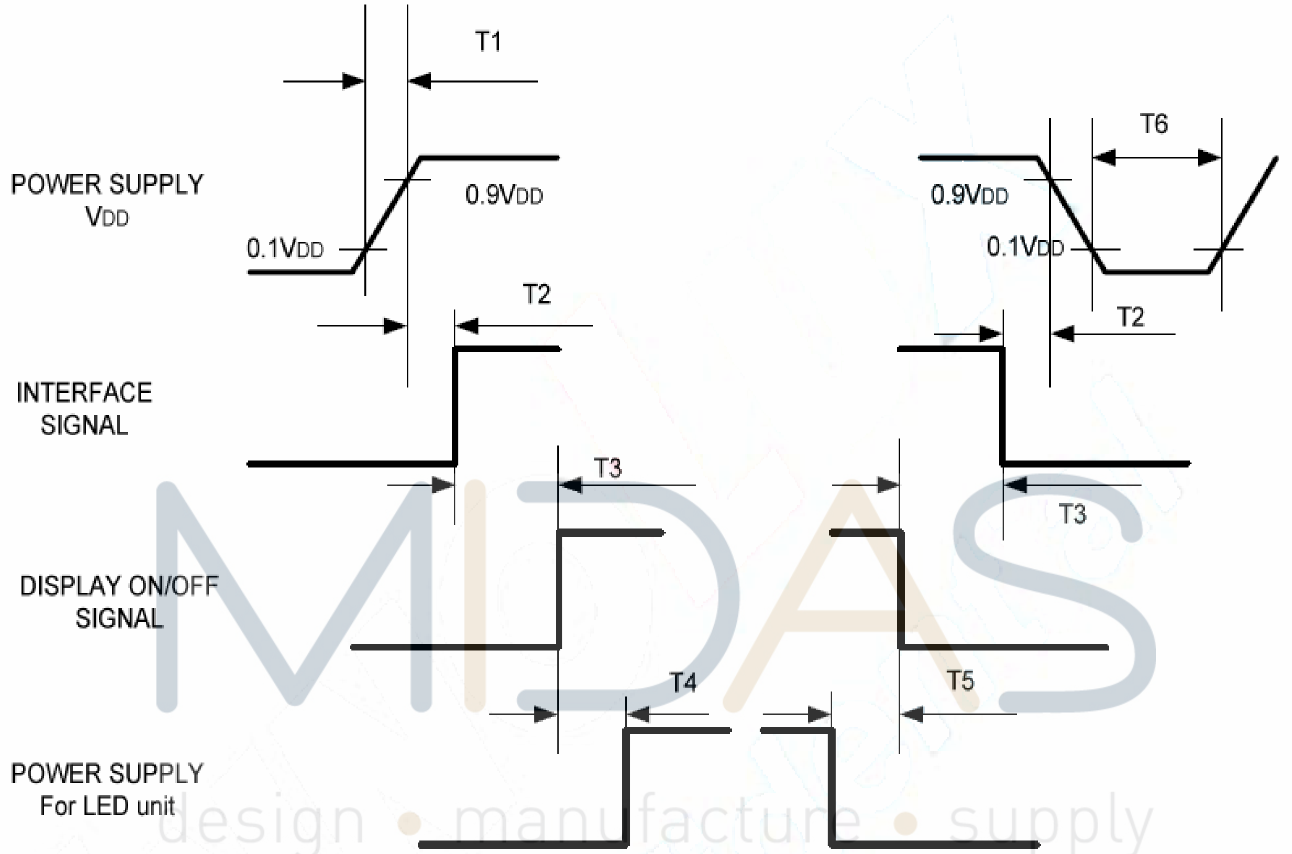
Item	Symbol	Values			Unit	Remark
		Min	TYP	max		
Voltage for LED Backlight	VL	25.2	27.9	31.5	V	Note 2
Current for LED Backlight	IL	18	20	22	mA	
LED life time	-	20,000	-	-	Hr	Note1

Note 1: The "LED life time" is defined as the module brightness decrease to 50% original brightness that the ambient temperature is 25℃ and IL =20mA. The LED lifetime could be decreased if operating IL is lager than 20 mA.

Note 2: The LED Supply Voltage is defined by the number of LED at Ta=25℃ and IL =20mA.

6.4 Power Sequence

To prevent a latch-up or DC operation of the LCD module, the power on/off sequence should be as the diagram below.



Symbol	Specification	Symbol	Specification
T1	0≦T1≦10 msec	T4	160 msec ≦T4
T2	0≦T2≦100 msec	T5	160 msec ≦T5
T3	0≦T3≦200 msec	T6	1 msec ≦T6

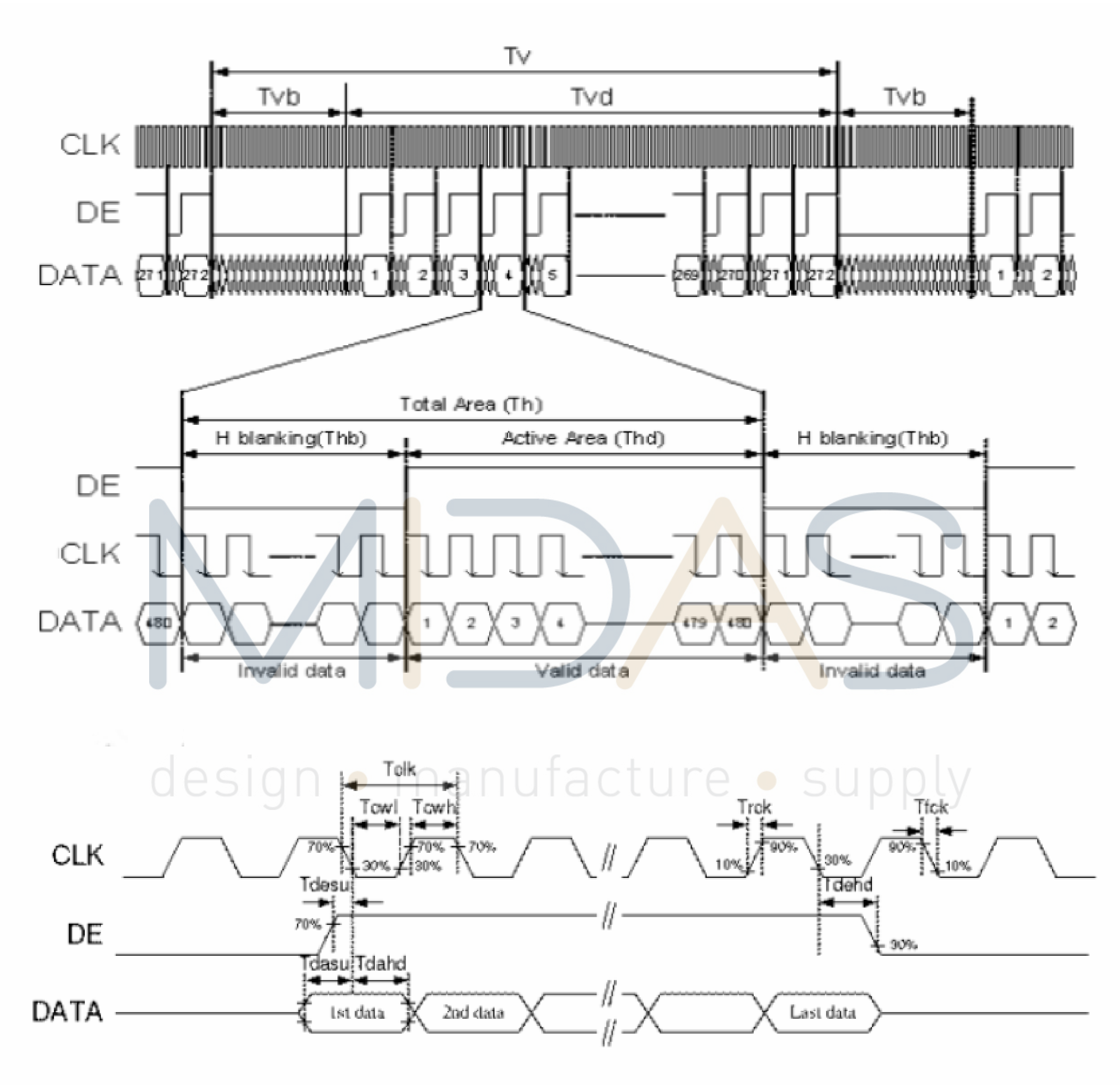
6.5 Timing Characteristics

6.5.1. Timing Conditions

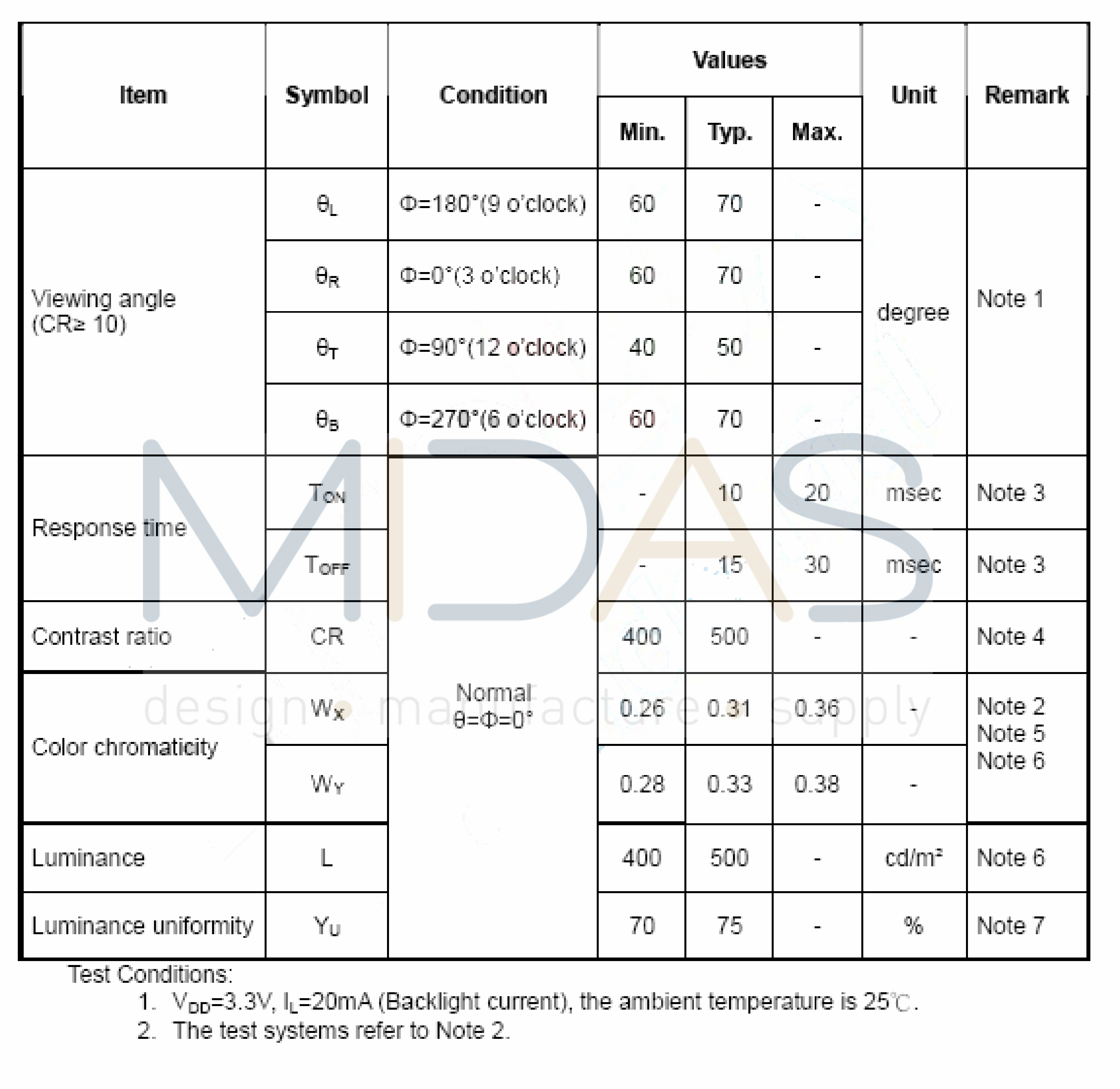
Parallel DE mode RGB input timing table

Parameter	Symbol	Value			Unit
		Min.	Typ.	Max.	
CLK frequency	fclk	7	9	12	MHz
DEV period time	Tv	277	288	400	H
DEV display area	Tvd	272			H
DEV blanking	Tvb	5	16	128	H
DEH period time	Th	520	525	800	CLK
DEH display area	Thd	480			CLK
DEH blanking	Thb	40	45	320	CLK
CLK cycle time	Tclk	83	110	143	ns
Clock width of high level	Tcwh	40	50	60	%
Clock width of low level	Tcwl	40	50	60	%
Clock rising time	trck		-	9	ns
Clock falling time	tfck		-	9	ns
Data Setup Time	tdesu	10	-	-	ns
Data Hold Time	tdahd	10	-	-	ns
DE Setup Time	tdesu	10	-	-	ns
DE Hold Time	tdehd	10	-	-	ns

6.5.2. Timing Diagram



7. Optical Characteristics



Item	Symbol	Condition	Values			Unit	Remark
			Min.	Typ.	Max.		
Viewing angle (CR≥ 10)	θ_L	Φ=180°(9 o'clock)	60	70	-	degree	Note 1
	θ_R	Φ=0°(3 o'clock)	60	70	-		
	θ_T	Φ=90°(12 o'clock)	40	50	-		
	θ_B	Φ=270°(6 o'clock)	60	70	-		
Response time	T_{ON}	Normal θ=Φ=0°	-	10	20	msec	Note 3
	T_{OFF}		-	15	30	msec	Note 3
Contrast ratio	CR		400	500	-	-	Note 4
Color chromaticity	W_X		0.26	0.31	0.36	-	Note 2 Note 5 Note 6
	W_Y		0.28	0.33	0.38	-	
Luminance	L		400	500	-	cd/m²	Note 6
Luminance uniformity	Y_U		70	75	-	%	Note 7

Test Conditions:

1. V_{DD}=3.3V, I_L=20mA (Backlight current), the ambient temperature is 25℃.
2. The test systems refer to Note 2.

Note 1: Definition of viewing angle range

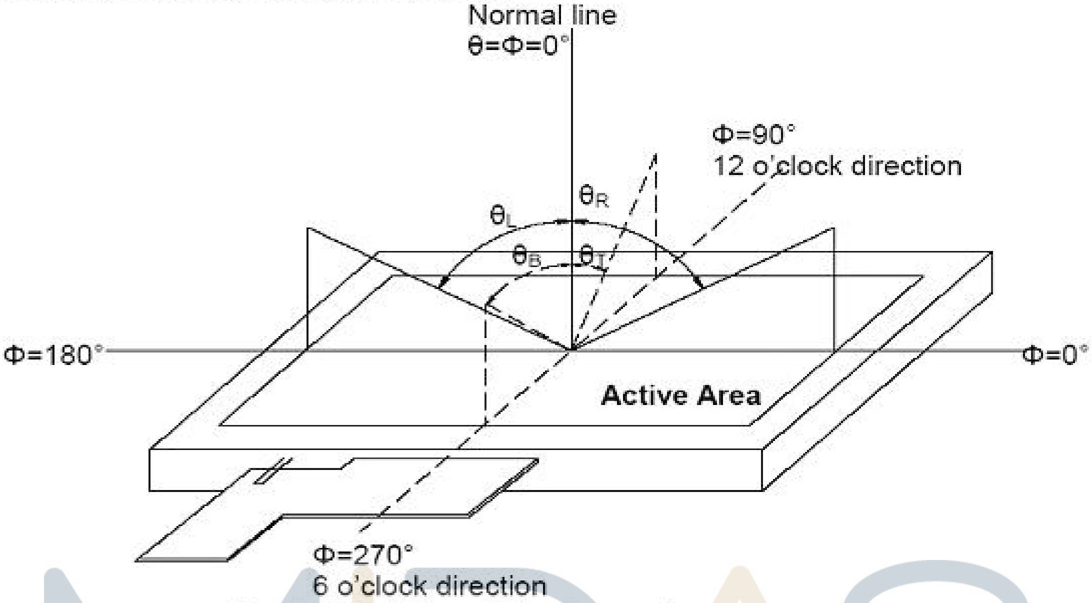


Fig. 4-1 Definition of viewing angle

Note 2: Definition of optical measurement system.
The optical characteristics should be measured in dark room. After 30 minutes operation, the optical properties are measured at the center point of the LCD screen. (Response time is measured by Photo detector TOPCON BM-7, other items are measured by BM-5A/Field of view: 1° /Height: 500mm.)

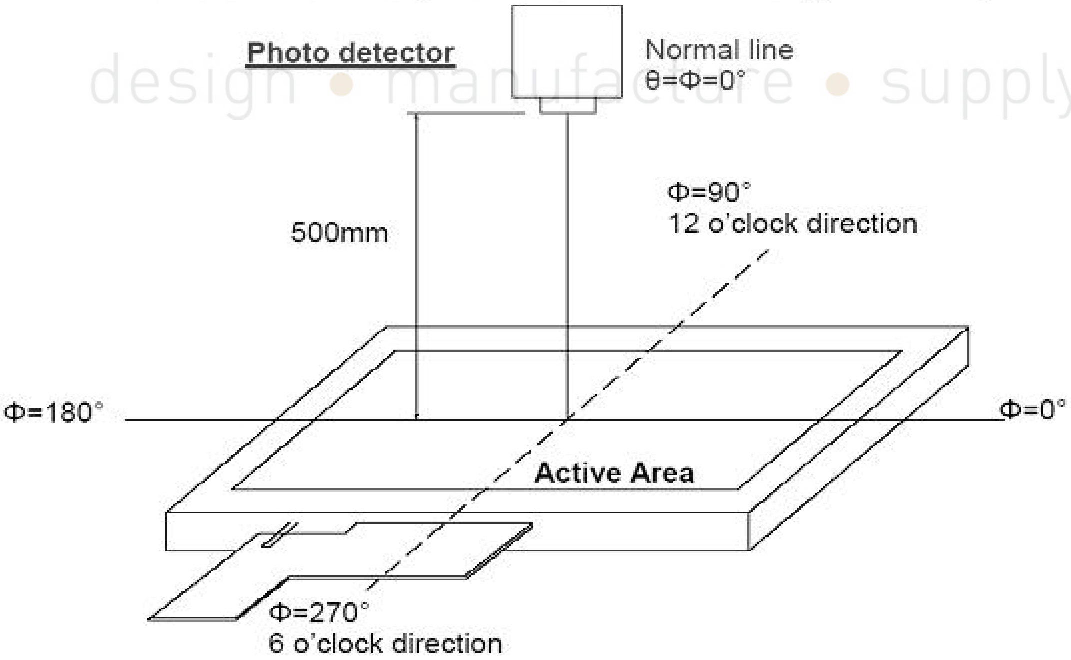


Fig. 4-2 Optical measurement system setup

Note 3: Definition of Response time

The response time is defined as the LCD optical switching time interval between "White" state and "Black" state. Rise time (T_{ON}) is the time between photo detector output intensity changed from 90% to 10%. And fall time (T_{OFF}) is the time between photo detector output intensity changed from 10% to 90%.

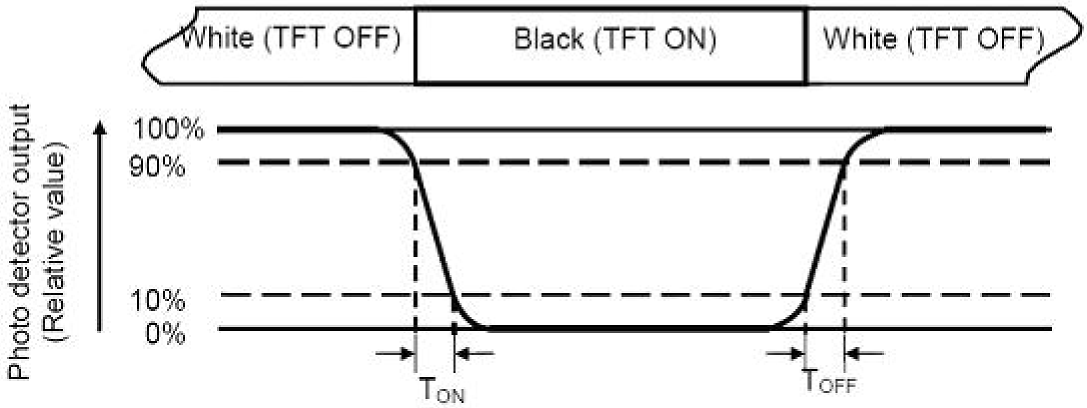


Fig. 4-3 Definition of response time

Note 4: Definition of contrast ratio

$$\text{Contrast ratio (CR)} = \frac{\text{Luminance measured when LCD on the "White" state}}{\text{Luminance measured when LCD on the "Black" state}}$$

Note 5: Definition of color chromaticity (CIE1931)
Color coordinates measured at center point of LCD.

Note 6: All input terminals LCD panel must be ground while measuring the center area of the panel. The LED driving condition is I_L=20mA.

Note 7: Definition of Luminance Uniformity

Active area is divided into 9 measuring areas (Refer to Fig. 4-4).Every measuring point is placed at the center of each measuring area.

$$Luminance\ \ Uniformity\ (Yu) = \frac{B_{min}}{B_{max}}$$

L-------Active area length W----- Active area width

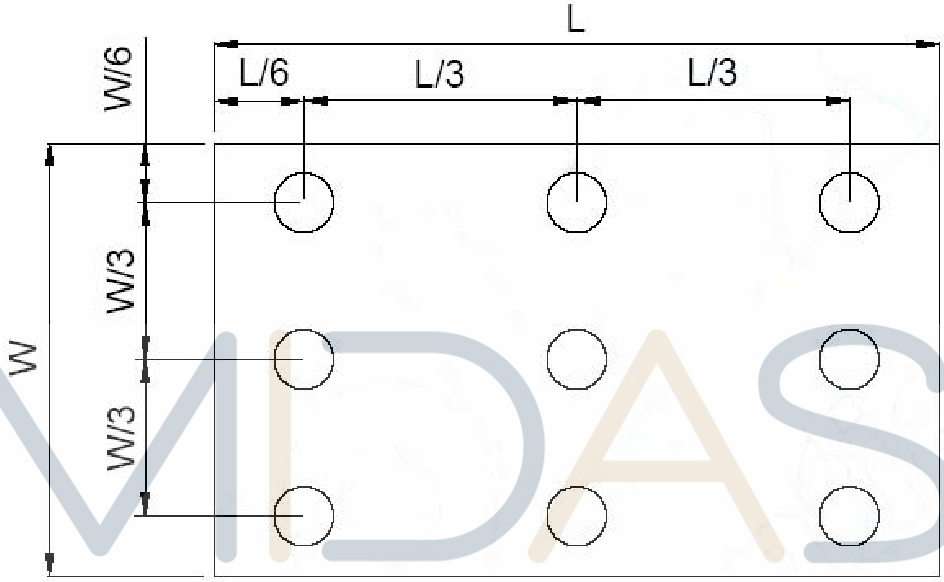


Fig. 4-4 Definition of measuring points

B$_{max}$: The measured maximum luminance of all measurement position.
B$_{min}$: The measured minimum luminance of all measurement position.

8. Absolute Maximum Ratings

Item	Symbol	Min	Typ	Max	Unit
Operating Temperature	T_{OP}	-20	—	+70	℃
Storage Temperature	T_{ST}	-30	—	+80	℃

9. Electrical Characteristics

Item	Symbol	Values			Unit	Remark
		Min	TYP	max		
Operating voltage	VDD	3.1	3.3	3.5	V	
Input high voltage	VIH	0.8*VDD	-	VDD	V	
Input low voltage	VIL	GND	-	0.2*VDD	V	
Output high voltage	VOH	VDD-0.3		VDD	V	
Output low voltage	VOL	0	-	0.3	V	
Current Consumption	IVCI	53.5	-	80.25	mA	VCC=2.5V
Power Consumption	PLCD	133.8		200-	mW	VCC=2.5V

10. Backlight Information

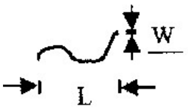
LED driving conditions

Item	Symbol	Values			Unit	Remark
		Min	TYP	max		
LED Voltage	VL	25.2	27.9	31.5	V	
LED Current	IF	-	20	-	MA	
Power Consumption	PLED	-	558	-	MW	

Note 1 : Ta = 25 _

Note 2 : Brightess to be decreased to 50% of the initial value

11. Inspection specification

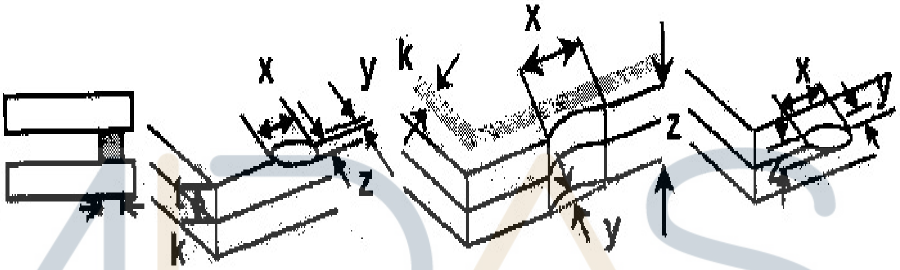
<table>
<tr><th>NO</th><th>Item</th><th>Criterion</th><th>AQL</th></tr>
<tr><td>01</td><td>Electrical Testing</td><td>1.1 Missing vertical, horizontal segment, segment contrast defect.
1.2 Missing character, dot or icon.
1.3 Display malfunction.
1.4 No function or no display.
1.5 Current consumption exceeds product specifications.
1.6 LCD viewing angle defect.
1.7 Mixed product types.
1.8 Contrast defect.</td><td>0.65</td></tr>
<tr><td>02</td><td>Black or white spots on LCD (display only)</td><td>2.1 White and black spots on display ≦0.25mm, no more than three white or black spots present.
2.2 Densely spaced: No more than two spots or lines within 3mm</td><td>2.5</td></tr>
<tr><td rowspan="2">03</td><td rowspan="2">LCD black spots, white spots, contamination (non-display)</td><td>3.1 Round type : As following drawing
$\Phi = (x + y) / 2$</td><td>2.5</td></tr>
<tr><td>3.2 Line type : (As following drawing)


<table>
<tr><th>Length</th><th>Width</th><th>Acceptable Q TY</th></tr>
<tr><td>---</td><td>W≦0.02</td><td>Accept no dense</td></tr>
<tr><td>L≦3.0</td><td>0.02＜W≦0.03</td><td rowspan="2">2</td></tr>
<tr><td>L≦2.5</td><td>0.03＜W≦0.05</td></tr>
<tr><td>---</td><td>0.05＜W</td><td>As round type</td></tr>
</table></td><td>2.5</td></tr>
<tr><td>04</td><td>Polarizer bubbles</td><td>If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction.
<table>
<tr><th>Size Φ</th><th>Acceptable Q TY</th></tr>
<tr><td>Φ≦0.20</td><td>Accept no dense</td></tr>
<tr><td>0.20＜Φ≦0.50</td><td>3</td></tr>
<tr><td>0.50＜Φ≦1.00</td><td>2</td></tr>
<tr><td>1.00＜Φ</td><td>0</td></tr>
<tr><td>Total Q TY</td><td>3</td></tr>
</table></td><td>2.5</td></tr>
</table>

<table>
<tr><th>NO</th><th>Item</th><th>Criterion</th><th>AQL</th></tr>
<tr><td>05</td><td>Scratches</td><td>Follow NO.3 LCD black spots, white spots, contamination</td><td></td></tr>
<tr><td>06</td><td>Chipped glass</td><td>

Symbols Define:
x: Chip length y: Chip width z: Chip thickness
k: Seal width t: Glass thickness a: LCD side length
L: Electrode pad length:

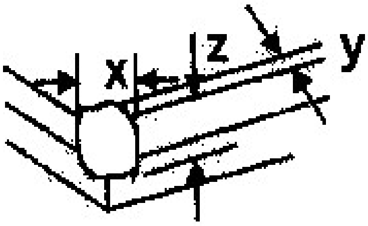
6.1 General glass chip :
6.1.1 Chip on panel surface and crack between panels:



<table>
<tr><th>z: Chip thickness</th><th>y: Chip width</th><th>x: Chip length</th></tr>
<tr><td>Z≦1/2t</td><td>Not over viewing area</td><td>x≦1/8a</td></tr>
<tr><td>1/2t＜z≦2t</td><td>Not exceed 1/3k</td><td>x≦1/8a</td></tr>
</table>

⊙If there are 2 or more chips, x is total length of each chip.

6.1.2 Corner crack:



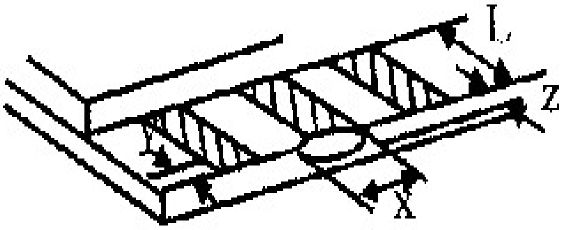
<table>
<tr><th>z: Chip thickness</th><th>y: Chip width</th><th>x: Chip length</th></tr>
<tr><td>Z≦1/2t</td><td>Not over viewing area</td><td>x≦1/8a</td></tr>
<tr><td>1/2t＜z≦2t</td><td>Not exceed 1/3k</td><td>x≦1/8a</td></tr>
</table>

⊙If there are 2 or more chips, x is the total length of each chip.

</td><td>2.5</td></tr>
</table>

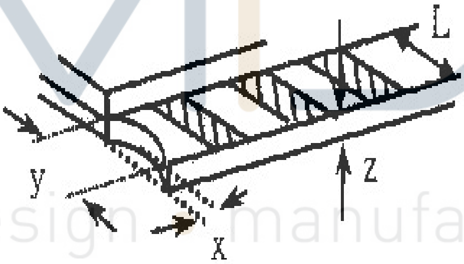
<table>
<tr><th>NO</th><th>Item</th><th>Criterion</th><th>AQL</th></tr>
<tr><td>06</td><td>Glass crack</td><td>

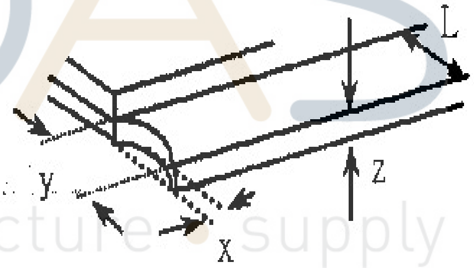
Symbols :
x: Chip length y: Chip width z: Chip thickness
k: Seal width t: Glass thickness a: LCD side length
L: Electrode pad length
6.2 Protrusion over terminal :
6.2.1 Chip on electrode pad :



<table>
<tr><th>y: Chip width</th><th>x: Chip length</th><th>z: Chip thickness</th></tr>
<tr><td>y≦0.5mm</td><td>x≦1/8a</td><td>0 ＜ z ≦ t</td></tr>
</table>

6.2.2 Non-conductive portion:

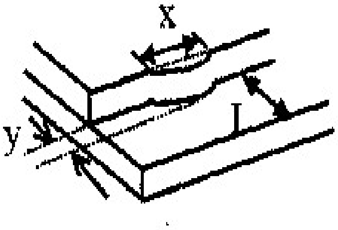




<table>
<tr><th>y: Chip width</th><th>x: Chip length</th><th>z: Chip thickness</th></tr>
<tr><td>y≦ L</td><td>x≦1/8a</td><td>0 ＜ z ≦ t</td></tr>
</table>

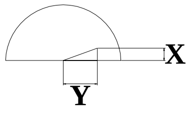
⊙If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.
⊙If the product will be heat sealed by the customer, the alignment mark not be damaged.

6.2.3 Substrate protuberance and internal crack.



<table>
<tr><th>y: width</th><th>x: length</th></tr>
<tr><td>y≦1/3L</td><td>x ≦ a</td></tr>
</table>

</td><td>2.5</td></tr>
</table>

NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
08	Backlight elements	8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn’t light or color wrong.	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination. 9.2 Bezel must comply with job specifications.	2.5 0.65
10	PCB、COB	10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB  **X * Y<=2mm^2**	2.5 2.5 0.65 2.5 2.5 0.65 0.65 2.5 2.5
11	Soldering	11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB.	2.5 2.5 2.5 0.65

NO	Item	Criterion	AQL
12	General appearance	12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.	2.5
		12.2 No cracks on interface pin (OLB) of TCP.	0.65
		12.3 No contamination, solder residue or solder balls on product.	2.5
		12.4 The IC on the TCP may not be damaged, circuits.	2.5
		12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it causes the interface pin to sever.	2.5
		12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color.	2.5
		12.7 Sealant on top of the ITO circuit has not hardened.	2.5
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 LCD pin loose or missing pins.	0.65
		12.10 Product packaging must the same as specified on packaging specification sheet.	0.65
		12.11 Product dimension and structure must conform to product specification sheet.	0.65

12. Precautions in use of LCD Modules

1. Avoid applying excessive shocks to the module or making any alterations or modifications to it.
2. Don’t make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
3. Don’t disassemble the LCM.
4. Don’t operate it above the absolute maximum rating.
5. Don’t drop, bend or twist LCM.
6. Soldering: only to the I/O terminals.
7. Storage: please storage in anti-static electricity container and clean environment.
8. Midas have the right to change the passive components
   (Resistors,capacitors and other passive components will have different appearance and color caused by the different supplier.)
9. Midas have the right to change the PCB Rev.

13. Material List of Components for RoHs

1. Midas hereby declares that all of or part of products, including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A：The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm
Above limited value is set up according to RoHS.						

2. Process for RoHS requirement：

   (1) Use the Sn/Ag/Cu soldering surface；the surface of Pb-free solder is rougher than we used before.

   (2) Heat-resistance temp.：

   Reflow：250℃, 30 seconds Max.；

   Connector soldering wave or hand soldering：320℃, 10 seconds max.

   (3) Temp. curve of reflow, max. Temp.：235±5℃；

   Recommended customer’s soldering temp. of connector：280℃, 3 seconds.

14. Recommendable storage

1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
2. Do not place the module near organics solvents or corrosive gases.
3. Do not crush, shake, or jolt the module